

### ENHANCING AR WAVEGUIDE PERFORMANCE: THE ROLE OF PROCESS OPTIMIZATION AND MATERIAL SCIENCE

AR/VR/MR - FROM DESIGN TO SYSTEM INTEGRATION AND MASS PRODUCTION, MAY 11-12, 2023

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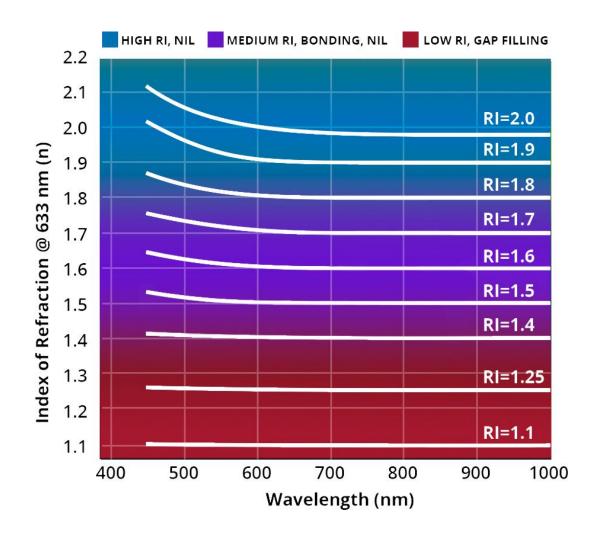


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## **PROCESS OPTIMIZATION AND MATERIAL SCIENCE**

- The efficiency of AR waveguides has a significant impact on the performance of the AR system particularly in terms of image quality, brightness, and battery life.
- Besides the optical design itself, the combined process optimization and material development (with the feedback loop) can help to achieve the targets.
  - Example 1): Minimizing Residual Layer Thickness (RLT) by process and material modifications and optimization
  - Example 2): Stray light control by material development
  - Example 3): Continuous material development

## **OPTICAL MATERIALS PRODUCTS RANGE**



n = 1.5 - 2.0 NIL resins, Optical coatings & light absorbing coatings

n = 1.4 - 1.6 Optical Bonding and Gap Fill

> n = 1.1 - 1.6 Optical Coatings

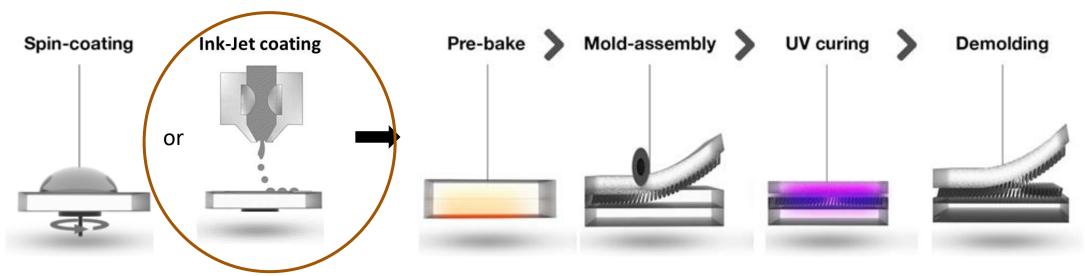




# EFFICIENCY IMPROVEMENTS BY PROCESS OPTIMIZATION



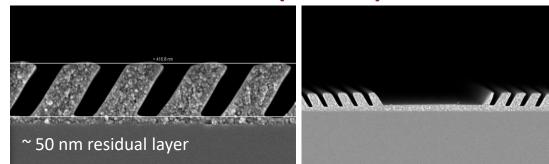
# **NIL PROCESS USING INK JETTING**



#### • High RI Optical NIL resins

- Refractive index from 1.55 to 1.92
- Spincoatable (IOC) and ink-jettable (IOP) resins
- Low haze and light scattering
- High transparency
- Thermally stable
- Low RLT

### IOC-133 (n = 1.9)

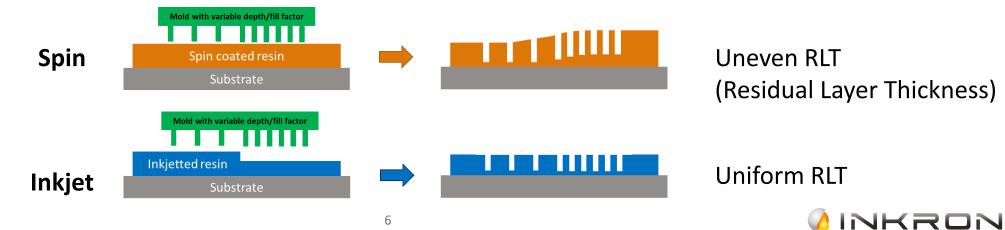


\*Slanted grating master manufactured and provided by NIL Technology AsP.



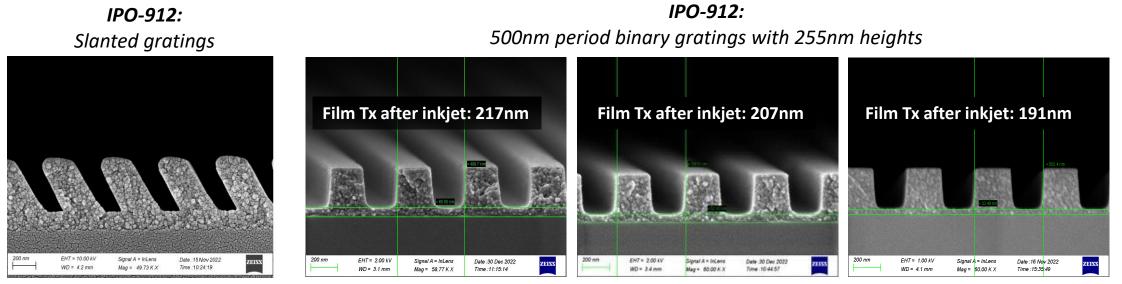
## **POTENTIAL BENEFITS OF INK JET+ NIL APPROACH**

| Inkjetting allows  | Benefit   | Note   |  |
|--|---|--|--|
| Use the coating only there where it is needed              | Material savings, Optical efficiency improvement                      | Might require changes for the optical design (edge effects etc.) |  |
| Freely selectable shape of coated area (on the same wafer) | Material savings, More units per wafer ? Panel size substrate         | Design freedom   |  |
| Variable coating layer<br>thicknesses on the same<br>wafer | Optimized local thickness for<br>targeted RLT, RLT layer<br>minimized | Improved Device Efficiency                                       |  |
| Use of different inks on the same wafer                    | Different product variants on the same wafer                          | Design Freedom, New designs requiring multiple inks              |  |



# NIL PROCESSABILITY - RLT OPTIMIZATION





RLT: ~57 nm



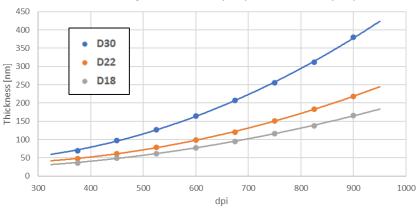
#### Inkjet conditions:

Printer: Suss PiXDRO LP50 Printhead: DMC Samba Substrate Temp: 25°C Ink Temp: 27°C Drop size: 4 pL (1dpd, 27-29V, 2.5µs)

- Optimized layer thickness allows RLT optimization
- RLT's as low as 30 nm can be achieved (with 1.9 RI NIL material)



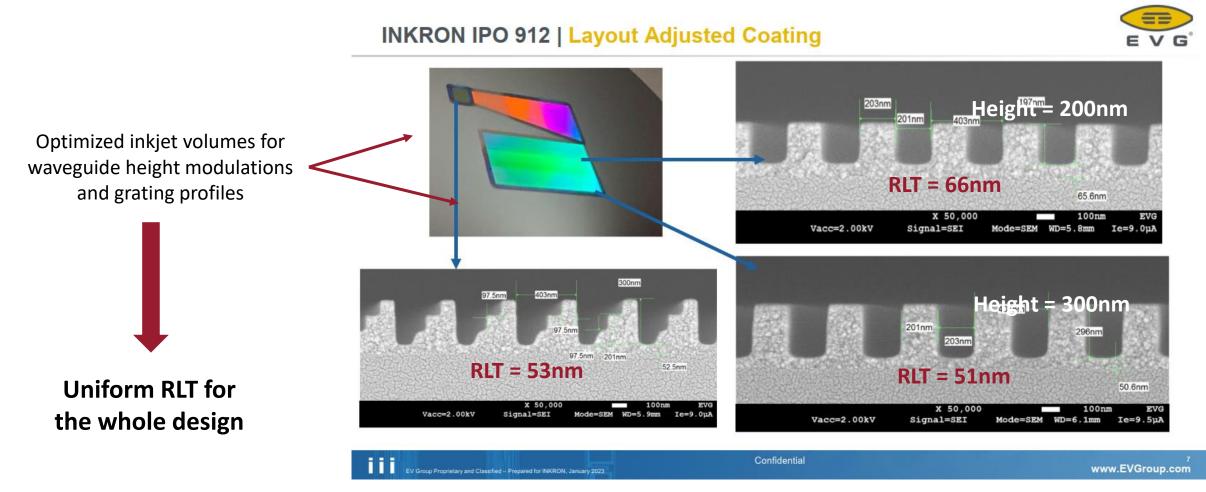
RLT: ~29 nm



IPO-912 Inkjet Resolution (DPI) vs. Thickness (nm)



# **RLT OPTIMIZATION OF A WAVEGUIDE**





This project has received funding from the European Union's Horizon 2020 research and innovation program under the Grant Agreement n°958472, project TINKER.



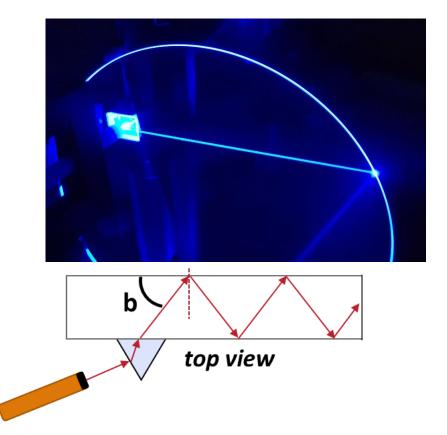


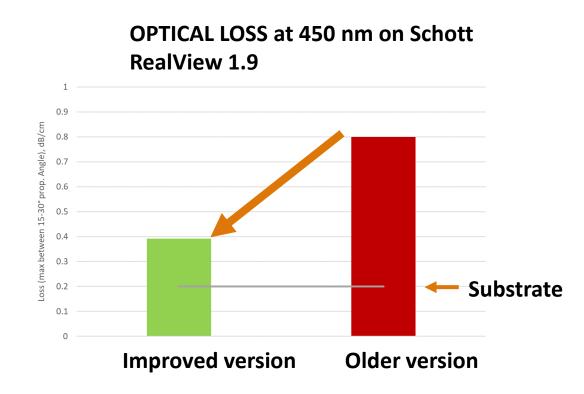
# MATERIAL OPTIMIZATION, PROCESS STABILITY AND OPTICAL LOSSES



### **IMPROVED OPTICAL PROPERTIES**

- Constant development of the nanofiller and resin system
- Significantly improved optical properties while maintaining the good processablity

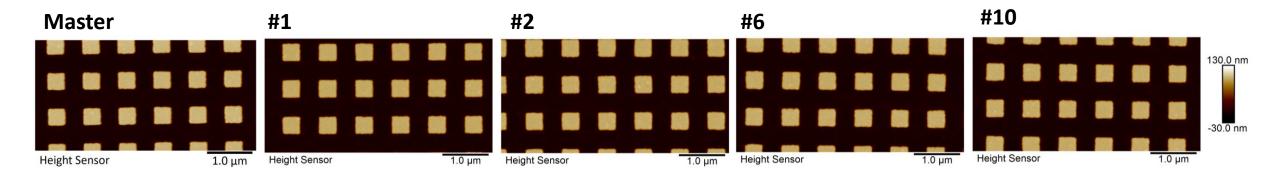






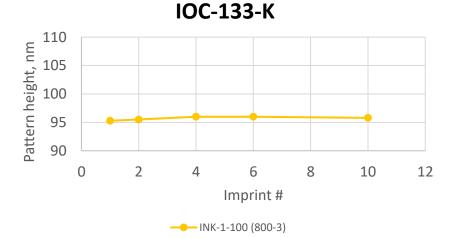
### CONTINUOUS DEVELOPMENT - IMPROVED DIMENSIONAL STABILITY – IOC-133-K

- Improved dimensional stability at <u>low layer thicknesses (<200nm)</u> implemented through formulation changes
- Layer thickness ca. 150 nm



| Structures                        | Master | #1   | #2   | #4   | #6   | #10  | Difference,<br>nm |
|-----------------------------------|--------|------|------|------|------|------|-------------------|
| Rect. pillars<br>Period:<br>800nm | 98.3   | 95.5 | 95.5 | 96.0 | 96.0 | 95.8 | +0.3              |

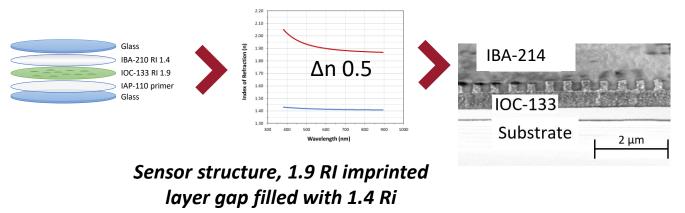
#### **Good pattern fidelity Negligible pattern height changes**



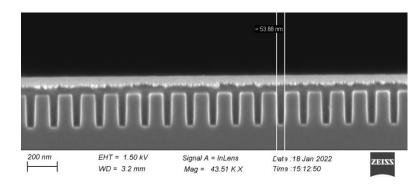


# **GAP FILLING, OPTICALLY CLEAR ADHESIVES**

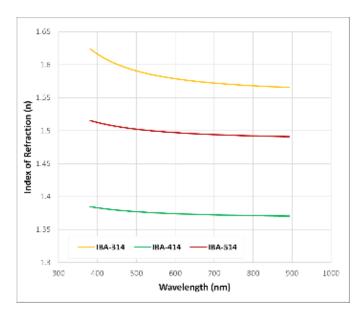
- Protective coatings and stacking
- Delta n between the gratings and the gap fill material
- Basic properties
  - RI 1.4, 1.5 and 1.6, no nano-particles
  - Excellent transparency, no haze or scattering
  - Excellent gap-filling properties (< 10 nm)
  - Spin-coating, possible to formulate for inkjet
  - Thermally stable, can withstand reflow temperatures



adhesive layer











## **ELIMINATION OF INTERNAL REFLECTIONS**

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## INDEX MATCHING BLACK MATERIAL ELIMINATES EDGE REFLECTIONS

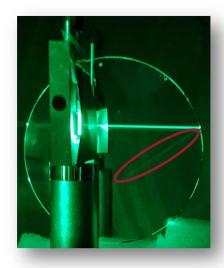


No black edge coating

~10% reflectance

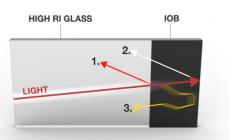


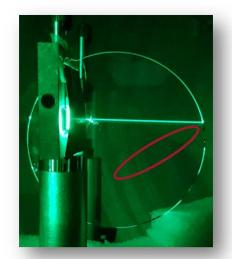
\*Schott 1.9 RealView glass wafers



"Standard" 1.5 RI black edge coating

~3% reflectance





1.9 RI black edge coating ↓ **~0% reflectance** 

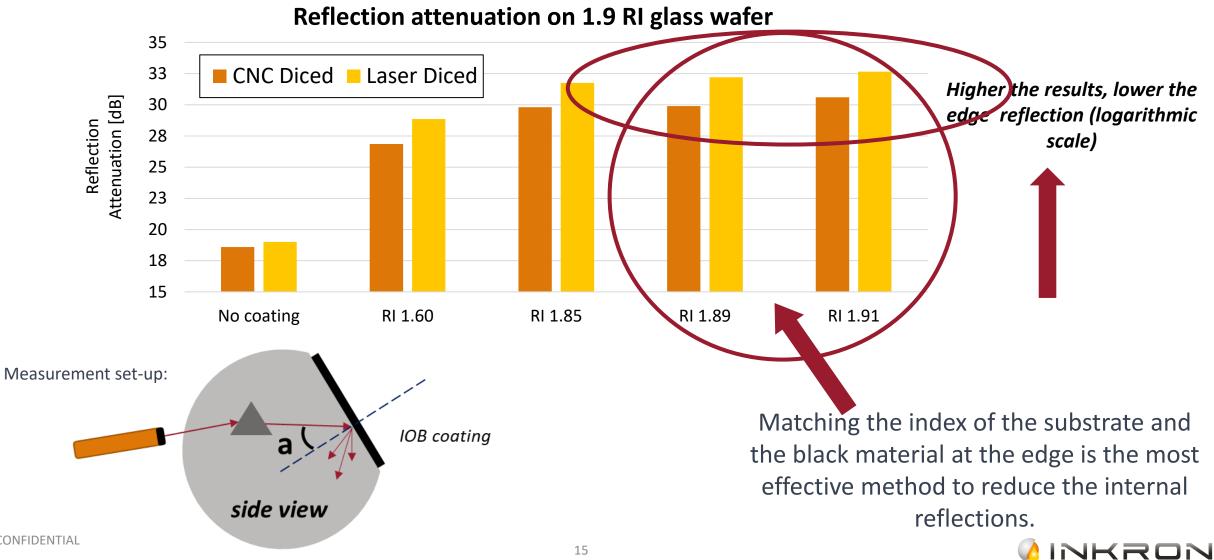
- Index matching of substrate and edge black material eliminates reflections caused by RI difference at the interface
- High Optical Density (OD) absorbs the light entering the blackening layer
- Balanced formulation removes scattering
- Both thermal and UV versions (RI 1.7-1.9)

### Benefit:

 Improved contrast and image quality

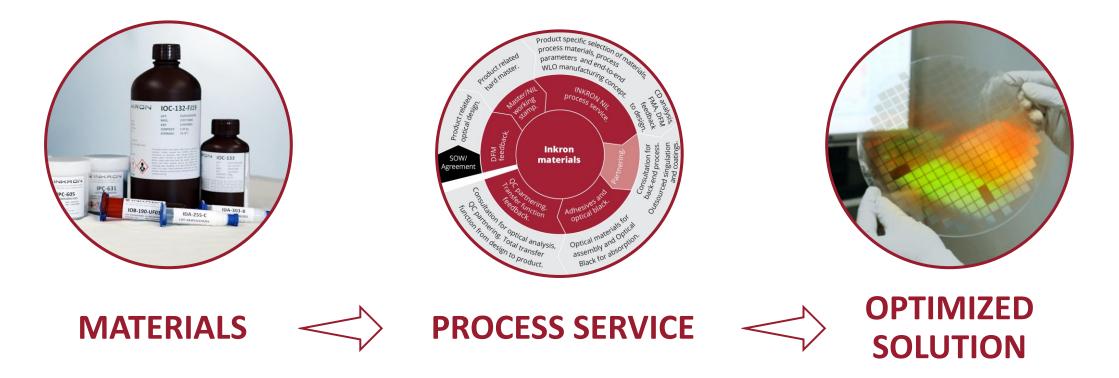


### **OPTICAL ANALYSIS OF INDEX MATCHING**



# CONCLUSION

- Inkjet + NIL is one of the key approaches for RLT optimization. Inkjet coating will be a major manufacturing method in combination with NIL process.
- Material development, integrated with process know-how and continuous process feedback, is a critical component of AR glass waveguide manufacturing and its progress.





# **THANK YOU**

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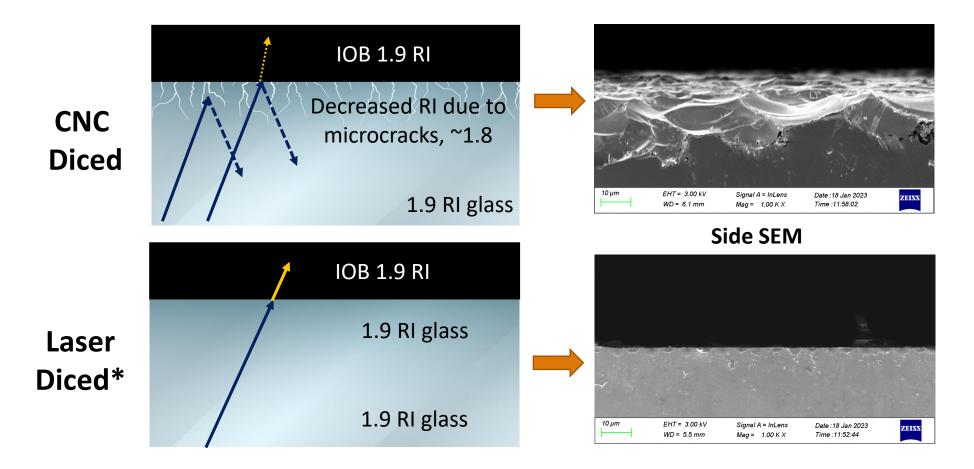
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## **EPIC QUESTIONS**

- What can we do for you ?
  - Materials for Wafer Level Optics
  - Material development for WLO
  - Prototyping NIL services
  - Open for joint R&D projects
- What can you do for us ?
  - If you work with diffractive optics, meta lenses, AR glasses etc. we would be keen to hear of you and discuss if there are any joint areas of interest

### **OPTICAL ANALYSIS OF EDGE QUALITY EFFECTS**



\*Corning Laser Technologies GmbH Laser nanoperforation, speed 60 m/min, edge roughness Ra = 0.33 μm



